



Semiconductor Device Type: C2X_SOIC_8_3.90mm_MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				4.00	100.00%		5.19%	
	Silicon	7440-21-3	4.00		100.00%		5.19%	51948
Lead Frame				20.00	100.00%		25.97%	
	Copper	7440-50-8	16.98		84.91%		22.06%	220551
	Iron	7439-89-6	0.46		2.28%		0.59%	5912
	Lead	7439-92-1	0.01		0.03%		0.01%	68
	Phosphorous	7723-14-0	0.03		0.13%		0.03%	340
	Zinc	7440-66-6	0.04		0.18%		0.05%	455
	Silver	7440-22-4	2.50		12.48%		3.24%	32416
Die Attach				4.50	100.00%		5.84%	
	Silver	7440-22-4	3.15		70.00%		4.09%	40909
	Diglycidylether of Bisphenol-F	54208-63-8	0.45		10.00%		0.58%	5844
	Modified Amine	Trade Secret	0.23		5.00%		0.29%	2922
	Epoxy Resin	Trade Secret	0.68		15.00%		0.88%	8766
Bonding Wire				0.50	100.00%		0.65%	
	Gold	7440-57-5	0.50		100.00%		0.65%	6493
Mold Compound				38.00	100.00%		49.35%	
	Silica Fused	60676-86-0	30.59		80.50%		39.73%	397273
	Epoxy Resin	Trade Secret	3.04		8.00%		3.95%	39481
	Epoxy, Cresol Novolac	29690-82-2	1.14		3.00%		1.48%	14805
	Phenol Resin	Trade Secret	3.04		8.00%		3.95%	39481
	Carbon Black	1333-86-4	0.19		0.50%		0.25%	2468
Plating				10.00	100.00%		12.99%	
	Tin	7440-31-5	10.00		100.00%		12.99%	129870
Totals				77.00			100.00%	100000

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